



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-04-27
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD6N65M2	TQDP*MQFPB6V	A	994X	2020-04-27
	Amount	UoM	Unit type	ST ECOPACK Grade
	330	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00460137	



Package Designator	Size	Nbr of instances	Shape	
SIP	6.50,6.10,2.30	3	gull wing	
Comment	TO 252 DPAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.02	die	61
Lead	1.71	soft solder	5173

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	1.71	Soft solder	5173
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	1.707	Soft solder	954698

Material Composition Declaration :						Mfr Item Name	TQDP*MQFPB6V					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	3.101	mg	supplier	die	Silicon(Si)	7440-21-3		2.979	mg	960658	9027
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.059	mg	19026	179
				supplier	metallisation	Nicke(Ni)	7440-02-0		0.020	mg	6450	62
				supplier	metallisation	Silver(Ag)	7440-22-4		0.007	mg	2257	22
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	322	3
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.014	mg	4515	42
Leadframe	M-004 Copper and its alloys	164.964	mg	supplier	passivation	Silicon oxide	7631-86-9		0.021	mg	6772	64
				supplier	alloy & coating	Copper(Cu)	7440-50-8		164.749	mg	998697	499239
				supplier	alloy & coating	Iron(Fe)	7439-89-6		0.076	mg	460	230
Soft solder	Solder	1.788	mg	SVHC	alloy & coating	Iron Phosphide(FeP)	26508-33-8		0.139	mg	843	421
				supplier	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	1.707	mg	954698	5173
				supplier	solder	Tin(Sn)	7440-31-5		0.036	mg	20134	109
Bonding wires	M-003 Aluminum and its alloys	0.356	mg	supplier	solder	Silver(Ag)	7440-22-4		0.045	mg	25168	136
				supplier	wire	Aluminium (Al)	7429-90-5		0.356	mg	1000000	1079
Bonding wires 2	M-003 Aluminum and its alloys	0.178	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.178	mg	1000000	539
Encapsulation	M-011 Other inorganic materials	158.568	mg	supplier	mold compound	Silica vitreous	60676-86-0		135.576	mg	855003	410836
				supplier	mold compound	Phenol resin Novolac	26834-02-6		7.928	mg	49997	24024
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		7.928	mg	49997	24024
				supplier	mold compound	Polyphenyl glycidyl ether co-dicyclopentadien	119345-05-0		5.550	mg	35001	16818
				supplier	mold compound	Benzaldehyde hydroxy polymer	106466-55-1		0.793	mg	5001	2403
				supplier	mold compound	Carbon black	1333-86-4		0.793	mg	5001	2403
connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3167